

A



NOTE 1. RECOMMENDED TEMPERATURE PROFILE FOR REFLOW
(REFER TO RIGHT FIG.)
USED REFLOW SYSTEM
: IR IN THE AIR OR NITROGEN
NO. OF CYCLES : 2 MAX
PEAK : 250℃
OVER 230℃ : 20~40s
PREHEAT : 150~180℃
90~120s

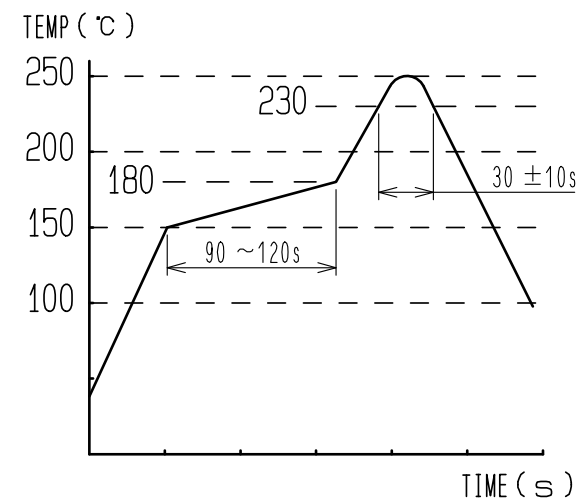
2. TEMPERATURE FOR SOLDERING IRON
: 280~300℃ WITHIN 2s

3. CO-PLANARITY SHALL BE 0.1mm MAX.

4. RECOMMENDED PCB THICKNESS IS 1.6mm.

5. RECOMMENDED SOLDER THICKNESS IS 0.15mm.

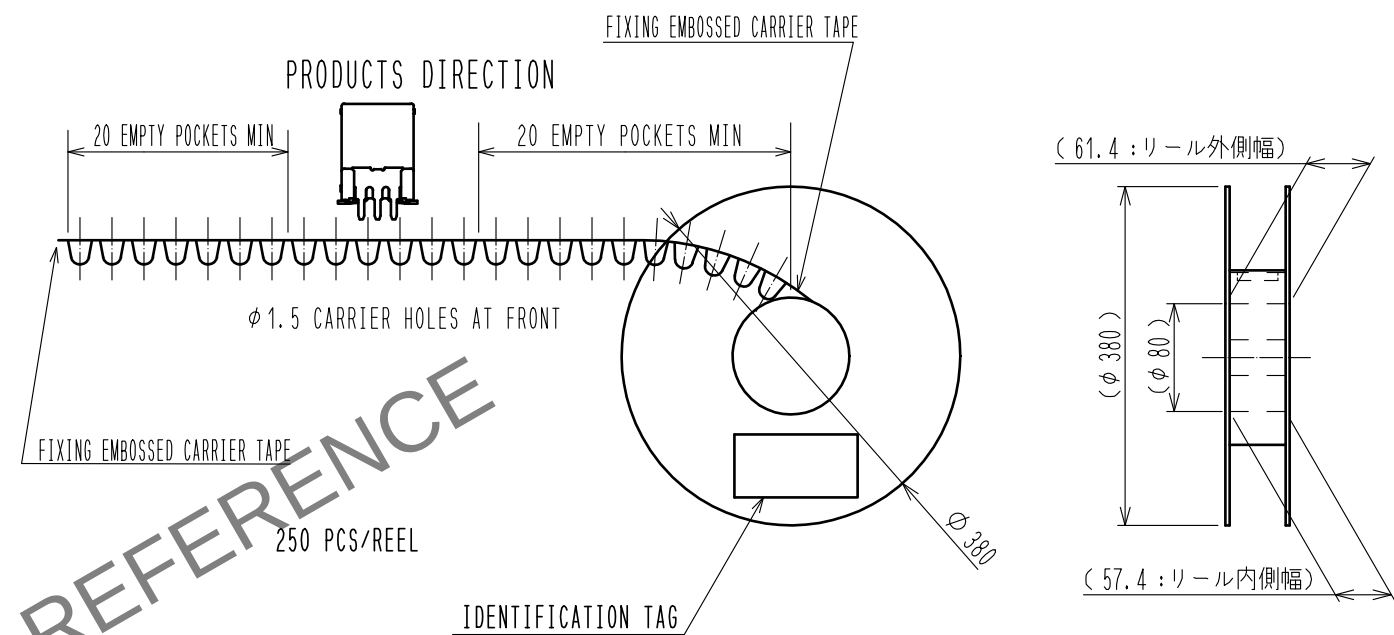
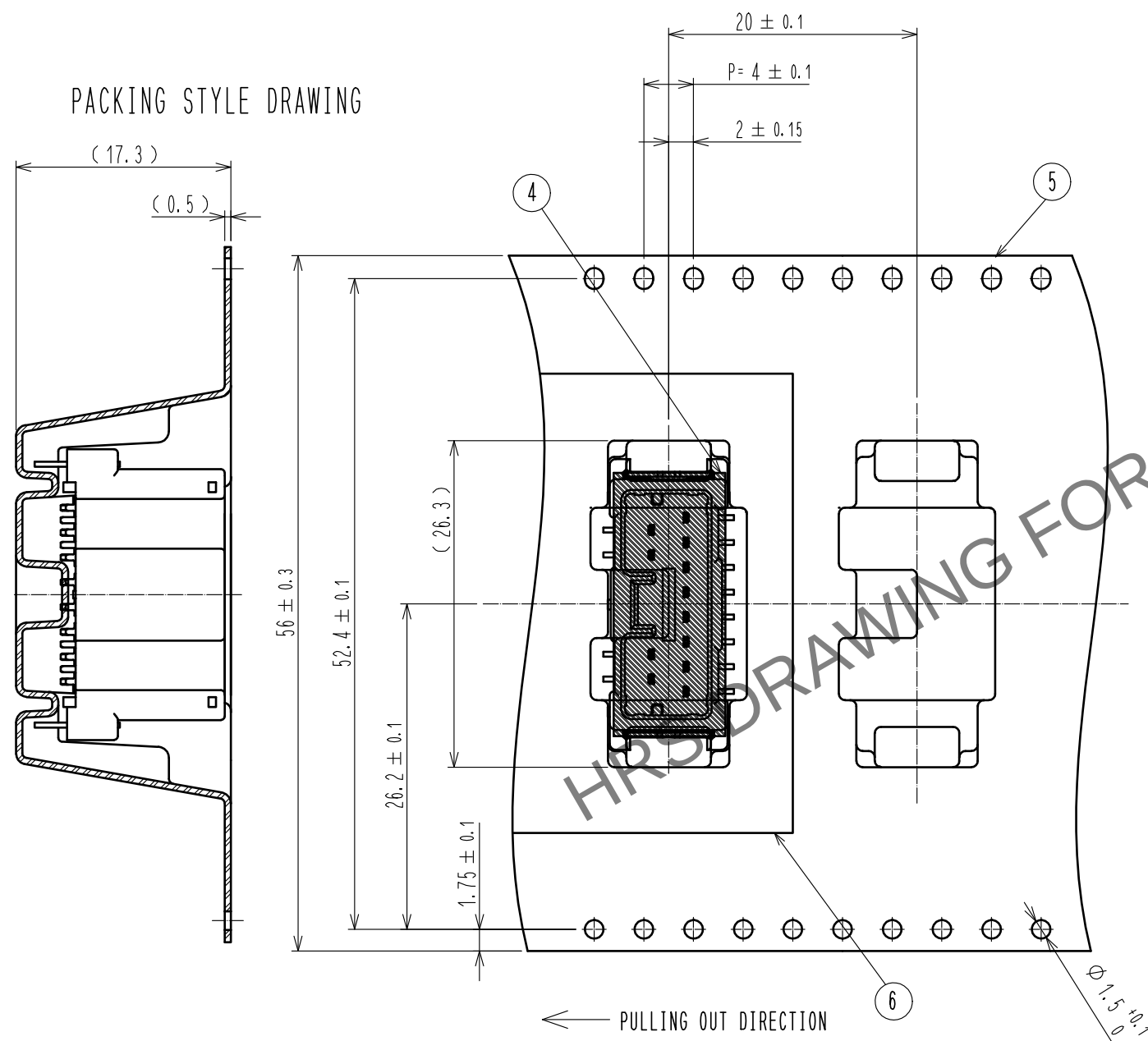
6. : Pattern prohibited area



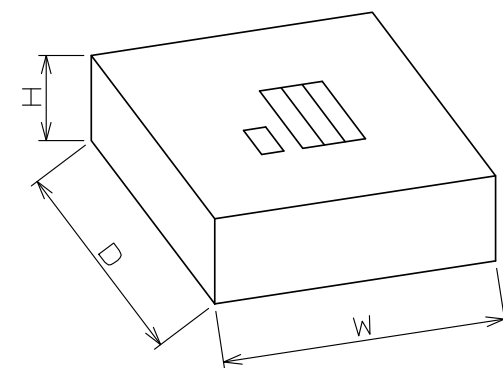
FORM HC0011-5-7	1	2	3	4	5	6	7	8
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PACKING STYLE

REEL DIMENSION(FREE)



CARDBOARD DIMENSION (FREE)



W=(405) (mm)
D=(405) (mm)
H= (63) (mm)

HRS

DRAWING NO.	EDC-368648-00-00
PART NO.	ZE05-12DP-2V
CODE NO.	CL752-2304-0-00

2/2